



Daily Newspaper

Dynex and Powersem

IGBT multi-chip technology co-operation

Dynex Semiconductor and Powersem have announced a collaboration agreement for the development, promotion and sale of new IGBT multi-chip technologies and applications. Dynex Semiconductor and Powersem have developed a new Trench gate EcoPak device, unveiled at PCIM, and are working on a range of products using the unique module facility



■ M. Chadda (Powersem) and M. LeGoff (Dynex Semiconductor)

developed by Powersem and the trench gate IGBT die and assembly facilities in Dynex.

Standard EMI filter for DC/DC

The new FDHC461 EMI filter from Apex Microtechnology is designed for use with DC/DC converters up to 7.5W output. Housed in an industry standard 8-pin package, the FDHC461 provides filtering to reduce input line reflected ripple current to within the limit of MIL-STD-461C, CE03 standards. This model is operational over the full military temperature range of -55 to +125°C. Key features include: 40 dB minimum differential mode rejection at 200 kHz, 3A throughput current, MIL-STD-704A through E power bus compatibility, all ceramic capacitors, surface mount magnetics and ultrasonically bonded aluminium wires.

Motorola focuses on motor control

MCUs, DSPs, Tools and Software

Sophisticated digital signal processors, microcontrollers and software enable energy efficiency, high levels of integration and cost-effectiveness for motor control

At PCIM exhibition Motorola introduces a comprehensive portfolio of embedded controllers and software optimized for motor control systems which are designed to meet the increasing demand for energy efficiency, as well as ease of programming and flexibility in designing electronic motor systems. "Motorola has differentiated itself by leveraging the experience gained over decades of working closely with leading automotive, industrial

Simulation and Management

Modern computer technology with the capability to perform complex simulation programmes gives the designer a decisive time advantage. Thus with good components available it is still most important to simulate the thermal requirements, improving reliability and system lifetime. As silicon becomes more and more efficient, still the remaining losses however arising need to be extracted in an efficient way so that the system offers improved reliability. This is achieved for example by having thinner die and eliminating unnecessary thermal resistances. The way to thermal optimisation has a wide choice of tools with simulation helping to improve time to market. The whole thermal chain

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Thursday, June 8

Events

8.30h – 16.40h

PCIM 2000 Conference

8.30-9.10h Keynote Paper: "Facts in the Liberalized Market - from the State of the Art to Future Trends", G. Brauner, Vienna University of Technology, Austria
CCN West Room Paris

9.00h – 17.00h

PCIM 2000 Exhibition

Hall 12

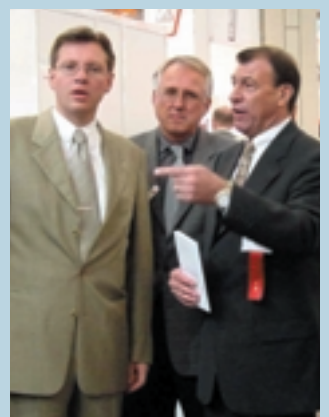
10.00h – 16.00h

Power Quality Forum

Hall 12

Job corner by the bistro in the middle of hall 12

International companies offering vacant jobs. Each company has its own section with detailed job descriptions. All of them are exhibitors, so contacts can be made easily.



■ On exhibition tour: Dr. Roland Fleck, (Economic Councillor City of Nuremberg) W. Hufnagel (NürnbergMesse), Gerd Zieroth (PCIM Organizer)

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Multiple chips in single packaging



ECO-PACS from Powersem offer a wide choice of circuit configurations and integrations of diode, thyristor, MOSFET and IGBT chips within a single package, thereby reducing the number of external connections. They provide isolation voltages of over 4000 VAC RMS, allow optimum heat transfer direct to the heat sink and are suitable for soldering on to printed circuit boards. The usage of DCB technology and planar glasspassivated silicon diffused chips in ECO-PACS leads to excellent long term reliability and thermal/load cycling capability. The ECO-PACS are rated 800 to 1800 V, 20 to 80 A and can easily replace up to 6 discrete devices and 3 power modules. The very flat package enables compact design and economic system solutions. Main applications for ECO-PAC are as supplies for DC power equipment, AC/DC motor drives, soft start capacitor charging and UPS.

Powersem
Stand 411

SERVICE NO. 60

Trench gate IGBT module



The Trench Gate ECO-PAC from Powersem is a robust non-punch-through trench gate n-channel, enhanced mode insulated gate bipolar transistor (IGBT) module designed for low power dissipation in a wide range of low to medium voltage applications such as power supplies and motor drives.

Trench gate technology offers significant improvements when compared with conventional planar IGBTs. The high impedance gate simplifies gate drive considerations, allowing operation directly from low power control circuitry. Low saturation voltages minimise power dissipation, thereby reducing the running cost of the overall system in which they are used. Typical applications include high frequency inverters for motor control, PWM, welding and heating equipment.

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SERVICE NO. 83